

DESCRIPTION

PT6302 is a dot matrix VFD Driver/Controller IC utilizing CMOS Technology specially designed to display characters, numerals, and symbols. PT6302 provides 35 dot matrix, 2 additional segment drivers and 16 grid drivers. 248 types of character data (CGROM), 8 types of character data (CGRAM), 16 display digits x 2 bits symbol data, 16 display digits x 8 bits register for character data display and 2 general output bits for static operation are provided. Pin assignments and application circuit are optimized for easy PCB layout and cost saving advantages.

APPLICATIONS

- Microcontroller peripheral device
- Audio/Video equipment

FEATURES

- CMOS technology
- Logic power supply: VDD=3.3V±10% or 5.0V±10%
- VFD drive power supply: VEE=-20V to -35V
- Built-in oscillation circuit (External RC)
- One-byte instruction execution (not including Data Write to RAM)
- Microcontroller interface
- Display contents:
 - Character generator ROM (CGROM): 5x7 Dots (248 Character data types)
 - Character generator RAM (CGRAM): 5x7 Dots (8 Character data types)
 - Additional data RAM (ADRAM): 16 Display digits x 2 Bits (Symbol data)
 - Data control RAM (DCRAM): 16 Display digits x 8 Bits (Character data display register)
 - General output port: 2 bits (Static operation)
- Display control function:
 - Display digits: 9 to 16 digits
 - Display duty (Contrast adjustment): 8 stages
 - All display lights: ON/OFF mode



BLOCK DIAGRAM



PT6302

APPLICATION CIRCUIT





ORDER INFORMATION

Valid Part Number	Package Type	Top Code
PT6302LQ-001	64 pins, LQFP	PT6302LQ-001
PT6302LQ-003	64 pins, LQFP	PT6302LQ-003
PT6302LQ-005	64 pins, LQFP	PT6302LQ-005
PT6302LQ-007	64 pins, LQFP	PT6302LQ-007
PT6302-001-H	Bare Chip	-
PT6302-003-H	Bare Chip	-
PT6302-005-H	Bare Chip	-
PT6302-007-H	Bare Chip	-

PIN CONFIGURATION



PIN DESCRIPTION

Pin Name	I/O	Description	Pin No.
SG5 to SG35 SG4 to SG1	0	Segment driver output pin	1 ~ 31 64 ~ 61
GR1 to GR16	0	Grid driver output pin	32 ~ 47
VEE	-	Power supply	48
VSS	-	Ground pin	49
OSCI		Oscillator input pin	50
OSCO	0	Oscillator output pin	51
RSTB	Ι	Reset input pin When this pin is set to "LOW", all functions are initialized.	52
CSB	I	Chip select input pin When this pin is set to "High" Level, the serial data transfer is disabled.	53
CLKB	I	Shift clock input pin The serial data is shifted at the rising edge of CLKB.	54
DIN	I	Serial data input pin	55
VDD	-	Positive power supply	56
P1 to P2	0	General purpose output pin	57 ~ 58
AD2 to AD1	0	Segment driver output pin	59 ~ 60



INPUT & OUTPUT CONFIGURATION

LOGIC INPUT PINS



LOGIC OUTPUT PINS



DRIVER OUTPUT PINS



V2.3



FUNCTION DESCRIPTION

OSCILLATION CIRCUIT

An oscillation circuit may be constructed by connecting external Resistor (R1) and Capacitor (C1) between the oscillator pins -- OSCO and OSCI. The RC time constant depends on the value of VDD voltage used. The target oscillation frequency is 2MHz. Please refer to the diagram below.



RESET FUNCTION

The Reset Function is enabled when the RSTB Pin is set to "Low" Level. All functions are initialized. The initial status of the various functions is given below:

- 1. Address of each RAM: Address "00"H
- 2. Data of each RAM: All contents are undefined.
- 3. General Output Ports: All General Output Ports are set to "LOW".
- 4. Display Digit: 16 Digits
- 5. Contrast Adjustment: 8/16
- 6. All Display Lights: OFF Mode
- 7. Segment Output: All Segment Outputs are set to "LOW".
- 8. AD Output: All AD Outputs are set to "LOW".

The RSTB Pin may be connected to either the microcontroller or an external Resistor and capacitor. For an external RC connection, please refer to the diagram below.





After reset, the PT6302 must be set according to the Initial Setting Flowchart shown below.





RELATIONSHIP BETWEEN SEGMENT DRIVERS SGN AND ADN (ONE DIGIT)

The following diagram best describes the relationship between the Segment Drivers -- SGn and ADn.



DATA TRANSFER

The Display Control Command and the data are written by an 8-bit serial data transfer. Please refer to the Write Timing Diagram below.



Note: When data is written into the RAM (DCRAM, ADRAM, CGRAM) in a continuous manner, the address are automatically incremented. Therefore it is not necessary to specify the first byte of the 2nd and later bytes when writing the RAM data.

When the CSB pin is set to "LOW" Level, data transfer operation is enabled. 8 bits of data are sequentially inputted into the DIN Pin (LSB first). The shift clock is inputted into CLKB pin and the shift register reads the data at rising edge of the shift clock. The internal load signals are automatically generated and the data is written to each register and RAM. Thus, it is not necessary to input load signals externally.

When the CSB Pin is set to "HIGH" Level, the data transfer operation is disabled. The data input when the CSB Pin changes from "HIGH" to "LOW" is recognized in 8-bit units.



COMMANDS

The following are the list of commands issued by PT6302. When data is written into the RAM (DCRAM, CGRAM, or ADRAM) in a continuous manner, the addresses are automatically incremented internally. It is therefore not necessary to specify the first byte.

		LSB		FIRS	БТ ВҮТ	Έ			MSB	LSB	SB SECOND BYTE MSB						MSB
NO.	COMMAND	В0	B 1	B2	B3	B4	B5	B6	B 7	В0	B1	B2	B 3	B4	B5	B6	В7
1	DCRAM DATA WRITE	X0	X1	X2	X3	1	0	0	0	C0	C1	C2	C3	C4	C5	C6	C7
										C0	C5	C10	C15	C20	C25	C30	*
										C1	C6	C11	C16	C21	C26	C31	*
2	CGRAM DATA WRITE	X0	X1	X2	*	0	1	0	0	C2	C7	C12	C17	C22	C27	C32	*
										C3	C8	C13	C18	C23	C28	C33	*
										C4	C9	C14	C19	C24	C29	C34	*
3	ADRAM DATA WRITE	X0	X1	X2	X3	1	1	0	0	C0	C1	*	*	*	*	*	*
4	GENERAL OUTPUT PORT SET	P1	P2	*	*	0	0	1	0								
5	DISPLAY DUTY SET	D0	D 1	D2	*	1	0	1	0								
6	NO. OF DIGITS SET	K0	K1	K2	*	0	1	1	0]							
7	ALL LIGHTS ON/OFF	L	Н	*	*	1	1	1	0]							
	TEST MODE	0	0	0	*	0	0	0	1								

Notes:

1. The Test Mode is not a user function, but an IC internal function

2. *=Not relevant

3. Xn=RAM address bit, n = 0 to 3

4. Cn=RAM character code bit, n=0 to 34

5. Pn=General output port status bit, n=1 to 2

6. Dn=Display duty bit, n=0 to 2

7. Kn=Number of digits bit, n=0 to 2

8. H=All lights on

9. L=All lights off

DATA CONTROL RAM (DCRAM) DATA WRITE COMMAND

The DCRAM Data Write Command is used to specify the address of the DCRAM and writes the character code of the CGROM and CGRAM. The DCRAM consists of 4 address bits which are used to store the CGRAM & CGROM character codes. The character codes specified by the DCRAM is converted to a 5 x 7 dot matrix character pattern via the CGROM and CGRAM. The DCRAM can store up to 16 characters. The DCRAM Data Write Command Format is shown below.

	LSB							MSB	
1st Byte	B0	B1	B2	B3	B4	B5	B6	B7	DCRAM Data Write Mode is selected and the
(1st)	X0	X1	X2	X3	1	0	0	0	OH)
	LSB							MSB	
2nd Byte	B0	B1	B2	B3	B4	B5	B6	B7	CGROM & CGRAM Character Codes are specified.
(2na)	C0	C1	C2	C3	C4	C5	C6	C7	(They are written into the DCRAM Address UH)

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PT6302

During a continuous data write operation from one DCRAM Address to the next, it is not necessary to specify the DCRAM address since they are automatically incremented; however, the character code must be specified. Please refer to the information below.

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	LSB							MSB	
2nd Byte	B0	B1	B2	B3	B4	B5	B6	B7	Character Code of CGRAM & CGROM are specified and
(3rd)	C0	C1	C2	C3	C4	C5	C6	C7	written into the DCRAM Address 1H.
	LSB				1	1	1	MSB	-
2nd Byte	B0	B1	B2	B3	B4	B5	B6	B7	Character Code of CGRAM & CGROM are specified and
(4th)	C0	C1	C2	C3	C4	C5	C6	C7	written into the DCRAM Address 2H.
				:					_
_	LSB							MSB	
2nd Byte	B0	B1	B2	B3	B4	B5	B6	B7	Character Code of CGRAM & CGROM are specified and
(17th)	C0	C1	C2	C3	C4	C5	C6	C7	written into the DCRAM Address FH.
	LSB						1	MSB	
2nd Byte	B0	B1	B2	B3	B4	B5	B6	B7	Character Code of CGRAM & CGROM are specified and
(18th)	C0	C1	C2	C3	C4	C5	C6	C7	rewritten into the DCRAM Address 0 H.
-									

where:

1. X0 (LSB) to X3 (MSB): DCRAM Address Bits (16 Characters) 2. C0 (LSB) to C7 (MSB): CGROM & CGRAM Character Code Bits (256 Characters)

Please refer to the table below for the GRID position and DCRAM Address setting relationship.

Hex	X0	X1	X2	X3	GRID Position
0	0	0	0	0	GR1
1	1	0	0	0	GR2
2	0	1	0	0	GR3
3	1	1	0	0	GR4
4	0	0	1	0	GR5
5	1	0	1	0	GR6
6	0	1	1	0	GR7
7	1	1	1	0	GR8
8	0	0	0	1	GR9
9	1	0	0	1	GR10
Α	0	1	0	1	GR11
В	1	1	0	1	GR12
С	0	0	1	1	GR13
D	1	0	1	1	GR14
E	0	1	1	1	GR15
F	1	1	1	1	GR16



CGRAM DATA WRITE COMMAND

The Character Generator RAM (CGRAM) Data Write Command is used to specify the CGRAM address (00H to 07H) and write the character pattern data. It consists of 3 address bits which is used to store the 5 x 7 dot matrix character patterns. The CGRAM can store up to 8 types of character patterns which may be displayed by specifying the Character Code (DCRAM Address). The CGRAM Data Write Command Format is given below.

LSB							MSB		
B0	B1	B2	B3	B4	B5	B6	B7	CGR/	AM Data Write Mode is selected and the CGRAM
X0	X1	X2	*	0	1	0	0	Addre	ess is specified (i.e. CGRAM Address = 00H).
LSB	1				1	1	MSB	٦	
B0	B1	B2	B3	B4	B5	B6	B7	1st C	Column Data is specified and rewritten into the
C0	C5	C10	C15	C20	C25	C30) *		AM Address oon.
LSB							MSB	_	
B0	B1	B2	B3	B4	B5	B6	B7	2nd	Column Data is specified and rewritten into the
C1	C6	C11	C16	C21	C26	C3 ⁻	1 *	CGF	AM Address oon.
LSB							MSB		
B0	B1	B2	B3	B4	B5	B6	B7	3rd (Column Data is specified and rewritten into the
C2	C7	C12	C17	C22	C27	C32	2 *	CGF	CAM Address UUH.
LSB						1	MSB	_	
B0	B1	B2	B3	B4	B5	B6	B7	4th (Column Data is specified and rewritten into the
C3	C8	C13	C18	C23	C28	C33	3 *	CGF	AM Address 00H.
LSB								MSB	
B0	B1	B2	B3	В	4	B5	B6	B7	5th Column Data is specified and rewritten into the
C4	C9	C14	C19		24 (229	C34	*	CGRAM Address 00H.
	LSB B0 X0 LSB B0 C0 LSB B0 C1 LSB B0 C2 LSB B0 C3 LSB B0 C3 LSB B0 C3	LSB B0 B1 X0 X1 LSB B0 B0 B1 C0 C5 LSB B0 B0 B1 C1 C6 LSB C1 B0 B1 C2 C7 LSB C8 B0 B1 C3 C8 B0 B1 C3 C8 B0 B1 C3 C8	LSB B0 B1 B2 X0 X1 X2 LSB	LSB B0 B1 B2 B3 X0 X1 X2 * LSB	LSB B0 B1 B2 B3 B4 X0 X1 X2 * 0 LSB * 0 B0 B1 B2 B3 B4 C0 C5 C10 C15 C20 LSB S S B0 B1 B2 B3 B4 C1 C6 C11 C16 C21 LSB S S S B0 B1 B2 B3 B4 C1 C6 C11 C16 C21 LSB S S S B0 B1 B2 B3 B4 C2 C7 C12 C17 C22 LSB S S S B0 B1 B2 B3 B4 C3 C8 C13 C18 C23 LSB S S S S B0 B1	LSB B0 B1 B2 B3 B4 B5 X0 X1 X2 * 0 1 LSB	LSB B0 B1 B2 B3 B4 B5 B6 X0 X1 X2 * 0 1 0 LSB * 0 1 0 0 B0 B1 B2 B3 B4 B5 B6 C0 C5 C10 C15 C20 C25 C30 LSB S C20 C25 C30 LSB S S S S S B0 B1 B2 B3 B4 B5 B6 C1 C6 C11 C16 C21 C26 C37 LSB S B4 B5 B6 G2 C7 C12 C17 C22 C27 C32 LSB S B1 B2 B3 B4 B5 B6 C3 C8 C13 C18 C23 C28 C33 LSB S S S S S	LSB MSB B0 B1 B2 B3 B4 B5 B6 B7 X0 X1 X2 * 0 1 0 0 LSB * 0 1 0 0 LSB B2 B3 B4 B5 B6 B7 C0 C5 C10 C15 C20 C25 C30 * LSB B2 B3 B4 B5 B6 B7 C0 C5 C10 C15 C20 C25 C30 * LSB MSB B6 B7 MSB B0 B1 B2 B3 B4 B5 B6 B7 C1 C6 C11 C16 C21 C26 C31 * LSB MSB B6 B7 G22 C7 C12 C17 C22 C27 C32 * LSB B1 B2 B3 B4 B5 <t< td=""><td>$\begin{array}{c c c c c c c c c c c c c c c c c c c$</td></t<>	$\begin{array}{c c c c c c c c c c c c c c c c c c c $

During a continuous data write operation from one CGRAM Address to the next, it is not necessary to specify the CGRAM address since they are automatically incremented; however, the character pattern data must be specified. The 2nd to the 6th character pattern data byte are considered as one data item, therefore 300ns is sufficient value for parameter tDOFF between bytes. Please refer to the information below.

	LSB							MSB	
2nd Byte	B0	B1	B2	B3	B4	B5	B6	B7	1st Column Data is specified and rewritten into the
(7th)	C0	C5	C10	C15	C20	C25	C30	*	CGRAM Address 01H.
				:					

	LSB							MSB	
6th Byte	B0	B1	B2	B3	B4	B5	B6	B7	5th Column Data is specified and rewritten into the
(11th)	C4	C9	C14	C19	C24	C29	C34	*	CGRAM Address 01H.

where:

2. C0 (LSB) to C34 (MSB): Character Pattern Data Bits (35 outputs/digit)

^{1.} X0 (LSB) to X2 (MSB): CGRAM Address Bits (8 Characters)



Please refer below for the CGROM Address and CGRAM Address Setting relationship.

HEX	X0	X1	X2	CGROM Address
00	0	0	0	RAM00(0000000B)
01	1	0	0	RAM01(0000001B)
02	0	1	0	RAM02(0000010B)
03	1	1	0	RAM03(00000011B)
04	0	0	1	RAM04(00000100B)
05	1	0	1	RAM05(00000101B)
06	0	1	1	RAM06(00000110B)
07	1	1	1	RAM07(00000111B)

The CGROM and CGRAM output area placement is given in the table below.



Note: The Character Generator ROM (CGROM) consists of 8 CGROM Address bits generating 5 x 7 dot matrix character patterns. It can store up to a maximum of 248 types of character patterns.



ADRAM DATA WRITE COMMAND

The Additional Data RAM (ADRAM) consists of 4 address bits used to store the symbol data. It can store up to 2 types of symbol patterns per digit. The symbol data specified by the ADRAM is directly outputted. The terminals to which the ADRAM data are outputted may be used as a cursor. The ADRAM command format is given below.

	LSB							MSB	
1st Byte	B0	B1	B2	B3	B4	B5	B6	B7	ADRAM Data Write Mode is selected and the
(1St)	X0	X1	X2	X3	1	1	0	0	OH)
	LSB							MSB	
2nd Byte	B0	B1	B2	B3	B4	B5	B6	B7	Symbol Data is specified and written into the ADRAM
(2110)	C0	C1	*	*	*	*	*	*	
During a c address s informatic	continu since t on belo LSB	ious da hey ar w.	ata write e autor	e operati natically	on from	one AE ented;	RAM A	Address er, the s MSB	to the next, it is not necessary to specify the ADRAM symbol data must be specified. Please refer to the
(3rd)	B0	B1	B2	B3	B4	B5	B6	B7	Address 1H.
· /	C0	C1	*	*	*	*	*	*	
	LSB							MSB	
2nd Byte	B0	B1	B2	B3	B4	B5	B6	B7	Symbol Data is specified and written into the ADRAM
(401)	C0	C1	*	*	*	*	*	*	
	LSB			:				MSB	
2nd Byte	B0	B1	B2	B3	B4	B5	B6	B7	Symbol Data is specified and written into the ADRAM
(1/th)	C0	C1	*	*	*	*	*	*	Address FH.
	LSB							MSB	
2nd Byte	B0	B1	B2	B3	B4	B5	B6	B7	Symbol Data is specified and rewritten into the
(1001)	C0	C1	*	*	*	*	*	*	

where:

1. X0 (LSB) to X3 (MSB): ADRAM address bits (16 Characters)

2. C0 (LSB) to C1 (MSB): Symbol data bits (2 symbol data per digit)



Please refer to the table below for the GRID and ADRAM Address relationship.

HEX	X0	X1	X2	X3	GRID Position
0	0	0	0	0	GR1
1	1	0	0	0	GR2
2	0	1	0	0	GR3
3	1	1	0	0	GR4
4	0	0	1	0	GR5
5	1	0	1	0	GR6
6	0	1	1	0	GR7
7	1	1	1	0	GR8
8	0	0	0	1	GR9
9	1	0	0	1	GR10
Α	0	1	0	1	GR11
В	1	1	0	1	GR12
С	0	0	1	1	GR13
D	1	0	1	1	GR14
E	0	1	1	1	GR15
F	1	1	1	1	GR16

GENERAL OUTPUT PORT SET COMMAND

The General Output Port Set Command is used to specify the general output port status. The general output port is used to control other input/output devices as well as turn on the LED Display. When the general output port is set to "HIGH", the output is equivalent to the VDD voltage. When the general output port is set to "LOW" Level, the output becomes ground potential. The command format is given below.

		LS	SВ			MS	В		
1st Byte	B0	B1	B2	B3	B4	B5	B6	B7	A General Output Port is selected and the output
-	P1	P2	*	*	0	0	1	0	status is specified.

where:

1. P1, P2: General output port

2. *=Not relevant

The following table shows the data setting in relation to the Status of the General Output Port

P1	P2	General Output Port Display Status
0	0	P1 ="LOW", P2="LOW" (see note 1)
1	0	P1="HIGH", P2="LOW"
0	1	P1="LOW", P2="HIGH"
1	1	P1="HIGH", P2="HIGH"

Note: The state when the power is applied or when the RSTB is inputted.



DISPLAY DUTY SET COMMAND

The Display Duty Set Command is used to write the display duty value to the duty cycle register. Using a 3-bit data, the display duty adjusts the contrast in 8 stages. When the power is turned ON or when the RSTB signal is inputted, the duty cycle register value is set to "0". It is advisable to always execute this command before turning on the display, after which the desired duty value may be set. The command format is given below.

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LSB

	LOD							IN 2B	
1st Byte	B0	B1	B2	B3	B4	B5	B6	B7	Display D
	D0	D1	D2	*	1	0	1	0	is specifie

splay Duty Set Mode is selected and the duty value specified.

where:

1. D0 (LSB) to D2 (MSB): Display duty data bits (8 stages)

2. *=Not relevant

The Relationship between the Setup Data and the Controlled GRID Duty is given in the table below.

HEX	D2	D1	D0	GRID Duty
0	0	0	0	8/16
1	0	0	1	9/16
2	0	1	0	10/16
3	0	1	1	11/16
4	1	0	0	12/16
5	1	0	1	13/16
6	1	1	0	14/16
7	1	1	1	15/16

The state when the Power is turned ON or when the RSTB signal is inputted

NUMBER OF DIGITS SET COMMAND

The Number of Digits Set Command is used to write the number of display digits into the display digit register. Using a 3-bit data, the Number of Digits Set Command can display 9 to 16 digits. When the power is turned ON or when the RSTB signal is inputted, the value is set to "0". It is advisable to always execute this command before the turning on the display. The command format is given below.

MSB

LSB

1st Byte

B0	B1	B2	B3	B4	B5	B6	B7	т
K0	K1	K2	*	0	1	1	0	n

The Number of Digits Set Mode is selected and the number of digit value is specified.

The tehle heless	, ahawa tha ralationahi	a haturaan tha aatur	s data and tha	a a metrolla d OD
The lable below	/ snows the relationsh	n neiween ine seint) oala ano ine	CONTOLEO GR
			adda ana ano	

HEX	K2	K1	K0	Number of Digits of GR
0	0	0	0	GR1 ~ GR16
1	0	0	1	GR1 ~ GR9
2	0	1	0	GR1 ~ GR10
3	0	1	1	GR1 ~ GR11
4	1	0	0	GR1 ~ GR 12
5	1	0	1	GR1~ GR13
6	1	1	0	GR1~ GR14
7	1	1	1	GR1~ GR15

The state when the Power is turned ON or when the RSTB signal is inputted.



DISPLAY LIGHT SET COMMAND

The Display Light Set Command is used to turn all display lights ON or OFF. All Display Lights ON Mode is primarily used for testing the display. The All Display Light OFF Mode is used for the blinking display and to prevent any malfunction when the power is turned ON. The general output port cannot be controlled by this command. The command format is given below.

	LSB							MSB	
1st Byte	B0	B1	B2	B3	B4	B5	B6	B7	The Display Light Set Command is selected
	L	Н	*	*	1	1	1	0	The Display Light Get Command is selected.

where:

1. L=All display lights are turned off

2. H=All display lights are turned on

3. *=Not relevant

The table below shows the SG and AD Display Status in relation to the Display Light Set Command data.

	Ц	SG and AD Display State		
	п	30 allu AD Display State		
0	0	Normal Display Mode	◀	The state when the power is applied or when the RSTB
1	0	All Outputs="LOW"		signal is inputted
0	1	All Outputs="HIGH"		
1	1	All Outputs="HIGH"	4	All Display Light ON Mode has the first priority.
			-	

RECOMMENDED SOFTWARE FLOWCHART



Notes:

1. Display light active mode (ex. 0111XX00B)

2. Test mode off (ex. 1000X000B)



ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Condition	Rating	Unit
Supply voltage 1	V _{DD}	-	-0.3 to 6.5	V
Supply voltage 2	V_{EE}	-	-35 to V _{DD} +0.3	V
Input voltage	V _{IN}	-	-0.3 to V _{DD} +0.3	V
Power dissipation	PD	Ta ≤ 25°C	541	mW
Output current 1	I _{O1}	GR1 to GR16	-40 to 0	mA
Output current 2	I _{O2}	AD1 to AD2	-20 to 0	mA
Output current 3	I _{O3}	SG1 to SG35	-10 to 0	mA
Output current 4	I _{O4}	P1 to P2	-4.0 to 4.0	mA
Operating temperature	Topr	-	-40 to +85	°C
Storage temperature	Tstg	-	-65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Supply voltage 1	V		4.5	5.0	5.5	V
Supply voltage 1	V DD		3.0	3.3	3.6	V
ParameterSupply voltage 1Supply voltage 2High level input voltageLow level input voltageCLKB frequencyOscillation frequencyFrame frequency	V	Power supply voltage=5V	-35	-	-20	V
Supply voltage 2	VEE	Power supply voltage=3.3V	-35	-	-20	V
High level input	V	Power supply voltage=5V All input pins except OSCI.	$0.7V_{DD}$	-	-	V
voltage	VIH	Power supply voltage=3.3V All input pins except OSCI.	$0.8V_{DD}$	-	-	V
Low level input	V	Power supply voltage=5V All input pins except OSCI.	-	-	$0.3V_{\text{DD}}$	V
voltage	VIL	Power supply voltage=3.3V All input pins except OSCI.	-	-	$0.2V_{\text{DD}}$	V
CLKB frequency	fc	Power supply voltage=5V	-	-	1.0	MHz
		Power supply voltage=3.3V	-	-	1.0	MHz
Oscillation frequency	face	Power supply voltage=5V R1=3.3KΩ, C1=47pF	1.5	2.0	2.5	MHz
Oscillation frequency	1050	Power supply voltage=3.3V R1=3.3KΩ, C1=39pF	1.5	2.0	2.5	MHz
Parameter Supply voltage 1 Supply voltage 2 High level input voltage Low level input voltage CLKB frequency Oscillation frequency Frame frequency RSTB input time Operating temperature	f	Power supply voltage=5V DIGIT=1 to 16, R1=3.3KΩ, C1=47pF	183	244	305	Hz
	IFR	Power supply voltage=3.3V DIGIT=1 to 16, R1=3.3KΩ, C1=39pF	183	244	Max. 5.5 3.6 -20 -20 -20 -20 -20 -20 -20 -20 -20 -20 -20 -20 -20 -20 $0.3V_{DD}$ $0.2V_{DD}$ 1.0 1.0 1.0 1.0 2.5 1.0 2.5 4 305 4 305 $ 85$ 85	Hz
PSTB input time	t	Power supply voltage=5V	200	-	-	
	^I RSON	Power supply voltage=3.3V	200	-	-	μο
Operating	т	Power supply voltage=5V	-40	-	85	°C
temperature	l opr	Power supply voltage=3.3V	-40	-	85	°C



DC ELECTRICAL CHARACTERISTICS

(Unless otherwise specified, V_{EE}=-35V, Ta=-40 to +85 $^\circ\!\mathrm{C}$)

Parameter	Symbol	Condition	Min.	Max.	Unit
High level input voltage	V	V _{DD} =5.0±10% CSB, CLKB, DIN, RSTB	$0.7V_{DD}$	-	V
riigh level liiput voitage	¥Н	V _{DD} =3.3±10% CSB, CLKB, DIN, RSTB	$0.8V_{\text{DD}}$	-	V
		V _{DD} =5.0±10% CSB, CLKB, DIN, RSTB	-	$0.3V_{\text{DD}}$	V
Low level input voltage	VIL	V _{DD} =3.3±10% CSB, CLKB, DIN, RSTB	-	$0.2V_{\text{DD}}$	V
High lovel input ourrent		V _{DD} =5.0±10% CSB, CLKB, DIN, RSTB; V _{IH} =V _{DD}	-1.0	1.0	μA
	ЧН	V _{DD} =3.3±10% CSB, CLKB, DIN, RSTB; V _{IH} =V _{DD}	-1.0	1.0	μA
Low level input current		V _{DD} =5.0±10% CSB, CLKB, DIN, RSTB; V _{IL} =0V	-1.0	1.0	μA
High level input voltage High level input current High level output voltage 1 High level output voltage 2 High level output voltage 3 High level output voltage 4 Low level output voltage 1	ıır.	V _{DD} =3.3±10% CSB, CLKB, DIN, RSTB; V _{IL} =0V	-1.0	1.0	μA
High lovel output veltage 1	V	V _{DD} =5.0±10% GR1 to GR16; I _{OH} =-30mA	V _{DD} -1.5	-	V
	V OH1	V _{DD} =3.3±10% GR1 to GR16; I _{OH} =-30mA	V _{DD} -1.5	-	V
High lovel output veltage 2		V _{DD} =5.0±10% AD1 to AD2, I _{OH} =-15mA	V _{DD} -1.5	-	V
	V OH2	V _{DD} =3.3±10% AD1 to AD2, I _{OH} =-15mA	V _{DD} -1.5	-	V
High lovel output veltage 2	V _{OH3}	V _{DD} =5.0±10% SG1 to SG35, I _{OH} =-6mA	V _{DD} -1.5	-	V
High level output voltage 5		V _{DD} =3.3±10% SG1 to SG35, I _{OH} =-6mA	V _{DD} -1.5	-	V
High lovel output veltage 4		V _{DD} =5.0±10% P1 to P2, I _{OH} =-5mA	V _{DD} -1.0	-	V
High level output voltage 4	V OH4	V _{DD} =3.3±10% P1 to P2, I _{OH} =-2.5mA	V _{DD} -1.0	-	V
		V _{DD} =5.0±10% GR1 to GR16, AD1 to AD2,SG1 to SG35	-	V _{EE} +1.0	V
	V OL1	V _{DD} =3.3±10% GR1 to GR16, AD1 to AD2; SG1 to SG35		V _{EE} +1.0	V
		V _{DD} =5.0±10% P1, P2, I _{OL} =15mA	-	1.0	V
	V OL2	V _{DD} =3.3±10% P1, P2, I _{OL} =7.5mA	-	1.0	V
		V_{DD} =5.0±10% V_{DD} , fosc=2MHz, No Load	-	4	mA
Current consumption 1	I _{DD1}	V_{DD} =3.3±10% V_{DD} , fosc=2MHz, No Load Duty 15/16, DIGIT 1 to 16; All outputs lights ON	-	3	mA
Current consumption 2		V_{DD} =5.0±10% V_{DD} , fosc=2MHz, No Load Duty 8/16, DIGIT 1 to 9; All outputs lights OFF	-	3	mA
	IDD2	V_{DD} =3.3±10% V_{DD} , fosc=2MHz, No Load Duty 8/16, DIGIT 1 to 9; All outputs lights OFF	-	2	mA



AC CHARACTERISTICS

(Unless otherwise specified, V_{EE}=-35V, Ta=-40 to +85 $^\circ\!\mathrm{C}$)

Parameter	Parameter Symbol Condition				Unit
CLKD avala time	fa	V _{DD} =5.0V+10%	1.0	-	μs
	IC	V _{DD} =3.3V+10%	1.0	-	μs
	4	V _{DD} =5.0V+10%	300	-	ns
CLKB pulse width	LCW	V _{DD} =3.3V+10%	300	-	ns
		V _{DD} =5.0V+10%	300	-	ns
DIN setup time	t _{DS}	V _{DD} =3.3V+10%	300	-	ns
DIN hald time		V _{DD} =5.0V+10%	300	-	ns
Din noid time	LDH	V _{DD} =3.3V+10%	300	-	ns
COD active times		V _{DD} =5.0V+10%	300	-	ns
CSB setup time	t _{CSS}	V _{DD} =3.3V+10%	300	-	ns
CSR hold time	+	V _{DD} =5.0V+10% R1=3.3KΩ, C1=47pF	16	-	μs
	CSH	V _{DD} =3.3V+10% R1=3.3KΩ, C1=39pF	16	-	μs
CSB wait time	t	V _{DD} =5.0V+10%	300	-	ns
	LCSW	V _{DD} =3.3V+10%	300	-	ns
Data processing time	+	V _{DD} =5.0V+10% R1=3.3KΩ, C1=47pF	8	-	μs
Data processing time	U OFF	V _{DD} =3.3V+10% R1=3.3KΩ, C1=39pF	8	-	μs
		V _{DD} =5.0V+10% When the RSTB signal is externally inputted from the microcontroller.	300	-	ns
	ι wrstb	V _{DD} =3.3V+10% When the RSTB signal is externally inputted from the microcontroller.	300	-	ns
DIN weit time		V _{DD} =5.0V+10%	300	-	ns
Din wait time	^L RSOFF	V _{DD} =3.3V+10%	300	-	ns
	+	V _{DD} =5.0V+10% Ci=100pF, tR=20% to 80%	-	4.0	μs
	٩	V _{DD} =3.3V+10% Ci=100pF, tR=20% to 80%	-	4.0	μs
All outputs siew rate	t_	V _{DD} =5.0V+10% Ci=100pF, tF=80% to 20%	-	4.0	μs
	ιF	V _{DD} =3.3V+10% Ci=100pF, tF=80% to 20%	-	4.0	μs
	+	V _{DD} =5.0V+10% Mounted in the Unit	100	-	
	^L PRZ	V _{DD} =3.3V+10% Mounted in the Unit	100	-	μs
VDD off time	5.0	-	ms		



TIMING CHARACTERISTICS

Parameter	Symbol	VDD=3.3V±10%	VDD=5.0±10%
High level input voltage	V _{IH}	0.8V _{DD}	0.7V _{DD}
Low level input voltage	V _{IL}	0.2V _{DD}	0.3V _{DD}

DATA TIMING



RESET (RSTB) TIMING



OUTPUT TIMING



DIGIT OUTPUT TIMING (16-DIGIT DISPLAY, DUTY= 15/16)



where: T=8/fosc



PT6302-001 CHARACTER FONT TABLE

MSB LSB	0	1	2	3	4	5	6	7	8	9	A	В	с	D	E	F
0	RAM0															
1	RAM1															
2	RAM2															
3	RAM3															
4	RAM4															
5	RAM5															
6	RAM6															
7	RAM7															
8																
9																
A																
В																
с																
D																
E																
F																

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PT6302-003 CHARACTER FONT TABLE

(MSB)	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000	RAMO															
0001	RAM1															
0010	RAM2															
0011	RAM3															
0100	RAM4															
0101	RAM5															
0110	RAM6															
0111	RAM7															
1000																
1001																
1010																
1011																
1100																
1101																
1110																
1111																

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PT6302-005 CHARACTER FONT TABLE

$\overline{\ }$		Up	per	D7	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1
		Nib	ble	D6	0	0	0	0	1	1	1	1	0	0	0	0	1	1	1	1
Lo	wer			D5	0	0	1	1	0	0	1	1	0	0	1	1	0	0	1	1
Nił	oble			D4	0	1	0	1	0	1	0	1	0	1	0	1	0	1	0	1
D3	D_2	Dı	D0		0	1	2	3	4	5	6	7	8	9	Α	В	С	D	Ε	F
0	0	0	0	0	CG-RAM (#0)	Ö		0											Ó	Ř
0	0	0	1	1	CG-RAM (#1)	100			Û				Ú	1				H	ß	:::::::::::::::::::::::::::::::::::::::
0	0	1	0	2	CG-RAM (#2)								10						Ū,	
0	0	1	1	3	CG-RAM (#3)	ĪL							a D							
0	1	0	0	4	CG-RAM (#4)		1 0		D				Ţ						Ö	
0	1	0	1	5	CG-RAM (#5)	đ													Õ	5
0	1	1	0	6	CG-RAM (#6)		83													
0	1	1	1	7	CG-RAM (#7)	I						U								Ô
1	0	0	0	8		÷		8		Š	h		â					1		
1	0	0	1	9		8				Y							Ð			
1	0	1	0	A																
1	0	1	1	В		00														
1	1	0	0	с		00									NA.					
1	1	0	1	D		Ŷ										4			ŝ	
1	1	1	0	E									A							
1	1	1	1	F							O	***			3	۵			Пk	*



PT6302-007 CHARACTER FONT TABLE

MSB LSB	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011
0000	RAM0											
0001	RAM1											
0010	RAM2											
0011	RAM3											
0100	RAM4											
0101	RAM5											
0110	RAM6											
0111	RAM7											
1000												
1001												
1010												
1011												
1100												
1101												
1110												
1111												



PAD CONFIGURATION



ALIGNMENT MARK DIMENSION







PAD LOCATION

Pad No.	Pad Name	Location				
1	SG5	[478.600, 2852.100]				
2	SG6	[50.000, 2637.500]				
3	SG7	[50.000, 2447.500]				
4	SG8	[50.000, 2257.500]				
5	SG9	[50.000, 2107.500]				
6	SG10	[50.000, 1967.500]				
7	SG11	[50.000, 1827.500]				
8	SG12	[50.000, 1687.500]				
9	SG13	[50.000, 1547.500]				
10	SG14	[50.000, 1407.500]				
11	SG15	[50.000, 1267.500]				
12	SG16	[50.000, 1127.500]				
13	SG17	[50.000, 987.500]				
14	SG18	[50.000, 847.500]				
15	SG19	[50.000, 707.500]				
16	SG20	[50.000, 567.500]				
17	SG21	[50.000, 427.500]				
18	SG22	[50.000, 287.500]				
19	SG23	[233.800, 50.000]				
20	SG24	[413.800, 50.000]				
21	SG25	[593.800, 50.000]				
22	SG26	[773.800, 50.000]				
23	SG27	[918.800, 50.000]				
24	SG28	[1063.800, 50.000]				
25	SG29	[1208.800, 50.000]				
26	SG30	[1353.800, 50.000]				
27	SG31	[1498.800, 50.000]				
28	SG32	[1643.800, 50.000]				
29	SG33	[1788.800, 50.000]				
30	SG34	[1933.800, 50.000]				
31	SG35	[2078.800, 50.000]				
32	GR1	[2223.800, 50.000]				
33	GR2	[2615.800, 267.200]				
34	GR3	[2615.800, 427.200]				
35	GR4	[2615.800, 587.200]				
36	GR5	[2615.800, 747.200]				
37	GR6	[2615.800, 907.200]				
38	GR7	[2615.800, 1057.200]				
39	GR8	[2615.800, 1187.200]				
40	GR9	[2615.800, 1317.200]				
41	GR10	[2615.800, 1447.200]				
42	GR11	[2615.800, 1577.200]				



Pad No.	Pad Name	Location
43	GR12	[2615.800, 1707.200]
44	GR13	[2615.800, 1837.200]
45	GR14	[2615.800, 1967.200]
46	GR15	[2615.800, 2097.200]
47	GR16	[2615.800, 2227.200]
48	VEE	[2615.800, 2357.200]
49	VSS	[2615.800, 2487.200]
50	OSCI	[2543.700, 2772.300]
51	OSCO	[2395.900, 2772.300]
52	RSTB	[2277.900, 2772.300]
53	CSB	[2167.900, 2772.300]
54	CLKB	[2057.900, 2772.300]
55	DIN	[1947.900, 2772.300]
56	VDD	[1837.900, 2772.300]
56	VDD	[1727.900, 2772.300]
57	P1	[1615.300, 2772.300]
58	P2	[1490.100, 2772.300]
59	AD2	[1258.600, 2852.100]
60	AD1	[1128.600, 2852.100]
61	SG1	[998.600, 2852.100]
62	SG2	[868.600, 2852.100]
63	SG3	[738.600, 2852.100]
64	SG4	[608.600, 2852.100]



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PACKAGE INFORMATION

64 PINS, LQFP



DETAILA

Symbol	Min.	Nom.	Max.						
A	-	-	1.60						
A1	0.05	0.15							
A2	1.35	1.45							
b	0.30	0.35	0.40						
С	0.09	0.16							
D	16.00 BSC								
D1		14.00 BSC							
E		16.00 BSC							
E1		14.00 BSC							
е		0.80 BSC							
L	0.45	0.75							
L1		1.00 REF							
θ	0 °	3.5°	7 °						

Notes:

1. All dimensions are in millimeter

2. Refer to JEDEC MS-022 BE



IMPORTANT NOTICE

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Princeton Technology Corp. 2F, 233-1, Baociao Road, Sindian, Taipei 23145, Taiwan Tel: 886-2-66296288 Fax: 886-2-29174598 http://www.princeton.com.tw